

# NPN Epitaxial Silicon Transistor

# KST<sub>10</sub>

#### **Features**

- VHF / UHF Transistor
- This is a Pb-Free Device

#### **ABSOLUTE MAXIMUM RATINGS** (Note 1)

Value are  $T_A = 25^{\circ}C$  unless otherwise noted.

Symbol	Parameter	Value	Units
V <sub>CBO</sub>	Collector-Base Voltage	30	V
V <sub>CEO</sub>	Collector-Emitter Voltage	25	V
V <sub>EBO</sub>	Emitter-Base Voltage	3	V
T <sub>STG</sub>	Storage Temperature	150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

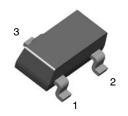
1. Refer to KSP10 for graphs.

#### THERMAL CHARACTERISTICS (Note 2)

Values are at T<sub>A</sub> = 25°C unless otherwise noted.

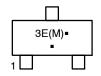
Symbol	Parameter	Max	Unit
$P_{D}$	Power dissipation	350	mW
	Derate Above 25°C	2.8	mW/°C
$R_{ hetaJA}$	Thermal Resistance, Junction to Ambient	357	°C/W

<sup>2.</sup> PCB Size: FR-4, 76 mm x 114 mm x 1.57 mm (3.0 inch x 4.5 inch x 0.062 inch) with minimum land pattern size.



- 1. Base
- Emitter
   Collector
- SOT-23 CASE 318

#### MARKING DIAGRAM



3E = Specific Device Code

M = Date Code

= Pb-Free Package

### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>	
KST10MTF	SOT-23 (Pb-Free)	3000 / Tape & Reel	

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

## **ELECTRICAL CHARACTERISTICS** Values are at T<sub>A</sub> = 25°C unless otherwise noted.

Symbol	Parameter	Test Condition	Min	Max	Unit
BV <sub>CBO</sub>	Collector-Base Breakdown Voltage	I <sub>C</sub> = 100 mA, I <sub>E</sub> = 0	30	_	V
BV <sub>CEO</sub>	Collector-Emitter Breakdown Voltage	I <sub>C</sub> = 1 mA, I <sub>B</sub> = 0	25	-	V
BV <sub>EBO</sub>	Emitter-Base Breakdown Voltage	I <sub>E</sub> = 10 mA, I <sub>C</sub> = 0	3	_	V
I <sub>CBO</sub>	Collector Cut-Off Current	V <sub>CB</sub> = 25 V, I <sub>E</sub> = 0	-	100	nA
I <sub>EBO</sub>	Emitter Cut-Off Current	V <sub>EB</sub> = 2 V, I <sub>C</sub> = 0	-	100	nA
h <sub>FE</sub>	DC Current Gain	V <sub>CE</sub> = 10 V, I <sub>C</sub> = 4 mA	60	_	
V <sub>CE</sub> (sat)	Collector-Emitter Saturation Voltage	I <sub>C</sub> = 4 mA, I <sub>B</sub> = 0.4 mA	-	0.5	V
V <sub>BE</sub> (on)	Base-Emitter On Voltage	V <sub>CE</sub> = 10 V, I <sub>C</sub> = 4 mA	-	0.95	V
f <sub>T</sub>	Current Gain Bandwidth Product	V <sub>CE</sub> = 10 V, I <sub>C</sub> = 4 mA, f = 100 MHz	650	_	MHz
C <sub>ob</sub>	Output Capacitance	V <sub>CB</sub> = 10 V, I <sub>E</sub> = 0, f = 1 MHz	-	0.7	pF
C <sub>rb</sub>	Common-Base Feedback Capacitance	V <sub>CB</sub> = 10 V, I <sub>E</sub> = 0, f = 1 MHz	-	0.65	pF
C <sub>c·rbb'</sub>	Collector-Base Time Constant	V <sub>CB</sub> = 10 V, I <sub>C</sub> = 4 mA, f = 31.8 MHz	-	9	pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

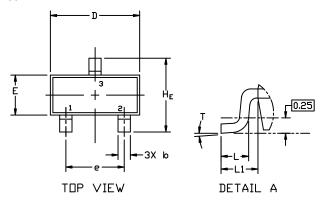


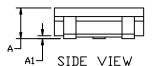


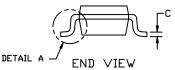
SOT-23 (TO-236) **CASE 318 ISSUE AT** 

**DATE 01 MAR 2023** 









#### NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M,1994.
- CONTROLLING DIMENSION: MILLIMETERS
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
- DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIMETERS		INCHES			
DIM	MIN.	N□M.	MAX.	MIN.	N□M.	MAX.
Α	0.89	1.00	1.11	0.035	0.039	0.044
A1	0.01	0.06	0.10	0.000	0.002	0.004
b	0.37	0.44	0.50	0.015	0.017	0.020
С	0.08	0.14	0.20	0.003	0.006	0.008
D	2.80	2.90	3.04	0.110	0.114	0.120
Ε	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.080
L	0.30	0.43	0.55	0.012	0.017	0.022
L1	0.35	0.54	0.69	0.014	0.021	0.027
HE	2.10	2.40	2.64	0.083	0.094	0.104
Т	0*		10°	0*		10°

# **GENERIC MARKING DIAGRAM\***

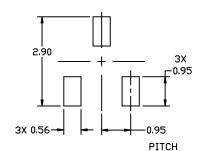


XXX = Specific Device Code

= Date Code

= Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "=", may or may not be present. Some products may not follow the Generic Marking.



RECOMMENDED MOUNTING FOOTPRINT

For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

## **STYLES ON PAGE 2**

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**DATE 01 MAR 2023** 

STYLE 1 THRU 5: CANCELLED	STYLE 6: PIN 1. BASE 2. EMITTER 3. COLLECTOR	STYLE 7: PIN 1. EMITTER 2. BASE 3. COLLECTOR	STYLE 8: PIN 1. ANODE 2. NO CONNECTION 3. CATHODE	ı	
STYLE 9:	STYLE 10:	STYLE 11: PIN 1. ANODE 2. CATHODE 3. CATHODE-ANODE	STYLE 12:	STYLE 13:	STYLE 14:
PIN 1. ANODE	PIN 1. DRAIN		PIN 1. CATHODE	PIN 1. SOURCE	PIN 1. CATHODE
2. ANODE	2. SOURCE		2. CATHODE	2. DRAIN	2. GATE
3. CATHODE	3. GATE		3. ANODE	3. GATE	3. ANODE
STYLE 15:	STYLE 16:	STYLE 17:	STYLE 18:	STYLE 19:	STYLE 20:
PIN 1. GATE	PIN 1. ANODE	PIN 1. NO CONNECTION	PIN 1. NO CONNECTION	I PIN 1. CATHODE	PIN 1. CATHODE
2. CATHODE	2. CATHODE	2. ANODE	2. CATHODE	2. ANODE	2. ANODE
3. ANODE	3. CATHODE	3. CATHODE	3. ANODE	3. CATHODE-ANODE	3. GATE
STYLE 21:	STYLE 22:	STYLE 23:	STYLE 24:	STYLE 25:	STYLE 26:
PIN 1. GATE	PIN 1. RETURN	PIN 1. ANODE	PIN 1. GATE	PIN 1. ANODE	PIN 1. CATHODE
2. SOURCE	2. OUTPUT	2. ANODE	2. DRAIN	2. CATHODE	2. ANODE
3. DRAIN	3. INPUT	3. CATHODE	3. SOURCE	3. GATE	3. NO CONNECTION
STYLE 27: PIN 1. CATHODE 2. CATHODE 3. CATHODE	STYLE 28: PIN 1. ANODE 2. ANODE 3. ANODE				

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